DEFECT DETECTION USING MULTIPLE SENSORS AND PARALLEL PROCESSING

ABSTRACT OF THE DISCLOSURE

Techniques for detecting defects on semiconductor wafers are described. The techniques involve a parallel processing system wherein a data distribution system contains data distribution nodes that are interconnected by multiple data transfer paths. This configuration allows data collected by any of the detectors to be routed to any one of a plurality of processing nodes. This in turn allows a variety of defect analysis algorithms to be implemented.